

Stannatech® SF 8

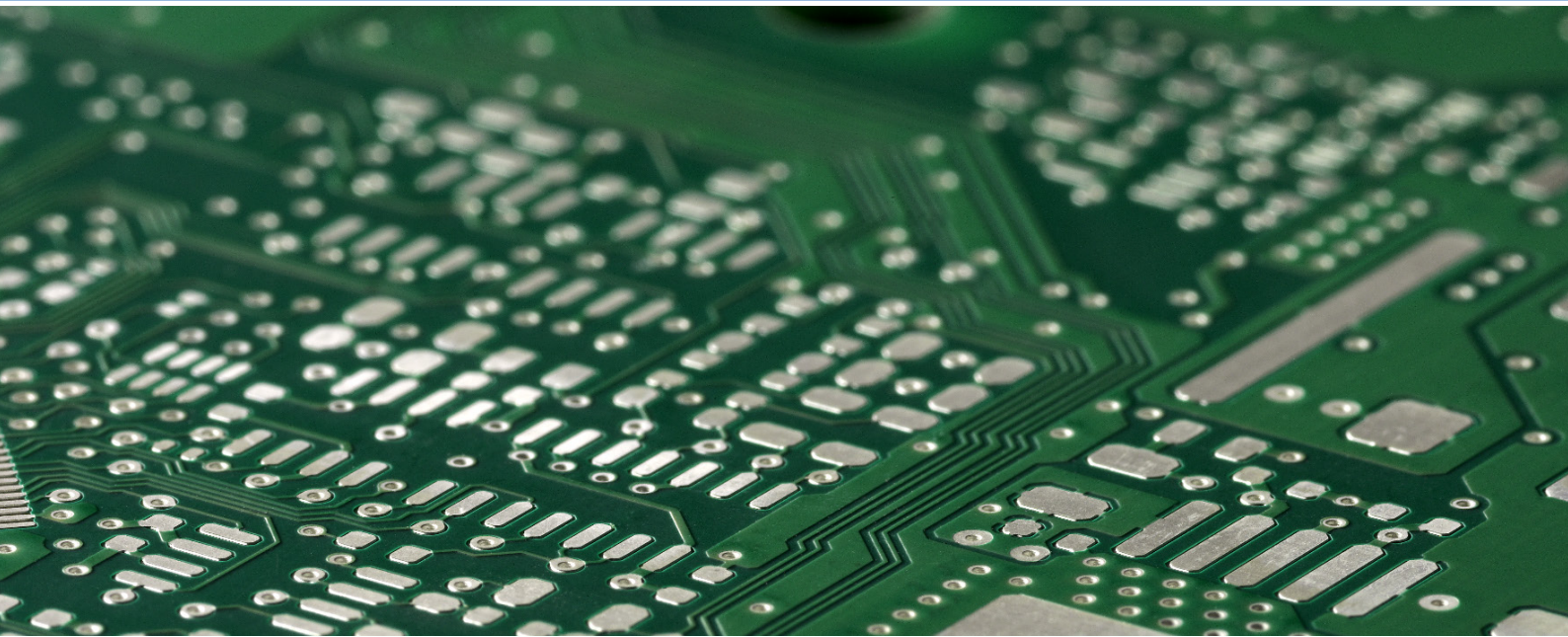
New immersion tin



Electronics

Final finishing technology

atotech.com



A Stannatech® evolution for vertical processing

New optimized immersion tin process

Based on the experience of the market leading Stannatech® 2000, Stannatech® SF 8 has been specifically developed to improve the process for vertical processing. By reducing the solution viscosity, the rinsing of the plating chemistry can be eased significantly and the solution exchange in small features is clearly improved.

Thanks to this the process can achieve an improved performance in terms of copper dissolution, solder mask attack and rinsability in particular when processed in vertical mode.

Stannatech® SF 8 maintains the market leading speed and quality expected from Atotech's highly versatile immersion tin finishes.

Features and benefits

- Low viscosity for improved rinsing
- Better solution exchange in small features
- Improved solder mask compatibility
- Easy and reliable process
- Stable bath performance and long bath life
- Designed to work with MKS' Atotech Crystallizer® tailored for vertical but also applicable in horizontal

Stannatech® SF 8 – Designed for vertical processing

Reduced copper dissolution

- Better solution exchange by low viscosity
- Lower copper dissolution in small structures
- Less sensitive to bath convection
- More robust in vertical processing

Improved solder mask compatibility

- Mild process solution
- Reduced solder mask attack
- Improved compatibility with different types of soldermasks
- Less sensitive to soldermask application

Improved rinsability

- Improved rinsability by low viscosity
- Lower rinse water consumption
- Improved cleanliness of processed panels
- Lower ion contamination values

Crystallizer concept

- Designed to work with Crystallizer concept
- Extended bath life
- Low chemistry consumption
- Cost saving by chemistry
- Stable performance over bath life

